

# LG-03IR4C94C-302BA-B1

## DATA SHEET

SPEC. NO. : SZ20071701  
DATE : 2020/07/17  
REV. : A/0

Approved By:

Checked By:

Prepared By:





## Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity	I <sub>e</sub>	25	30	---	mW/sr	I <sub>F</sub> =50mA (Note 1,3)
Viewing Angle	1/2	---	30	---	deg	(Note 2)
Peak Wavelength		---	940	---	nm	I <sub>F</sub> =20mA
Spectral Line Half- Width		---	50	---	nm	I <sub>F</sub> =20mA
Forward Voltage	V <sub>F</sub>	---	1.25	1.5	V	I <sub>F</sub> =50mA
Reverse Current	I <sub>R</sub>	---	---	100	μA	V <sub>R</sub> =5V

### Note:

1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
2. 1/2 is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
3. The I<sub>e</sub> guarantee should be added ±15% tolerance.

## Recommended Wave Soldering Profile

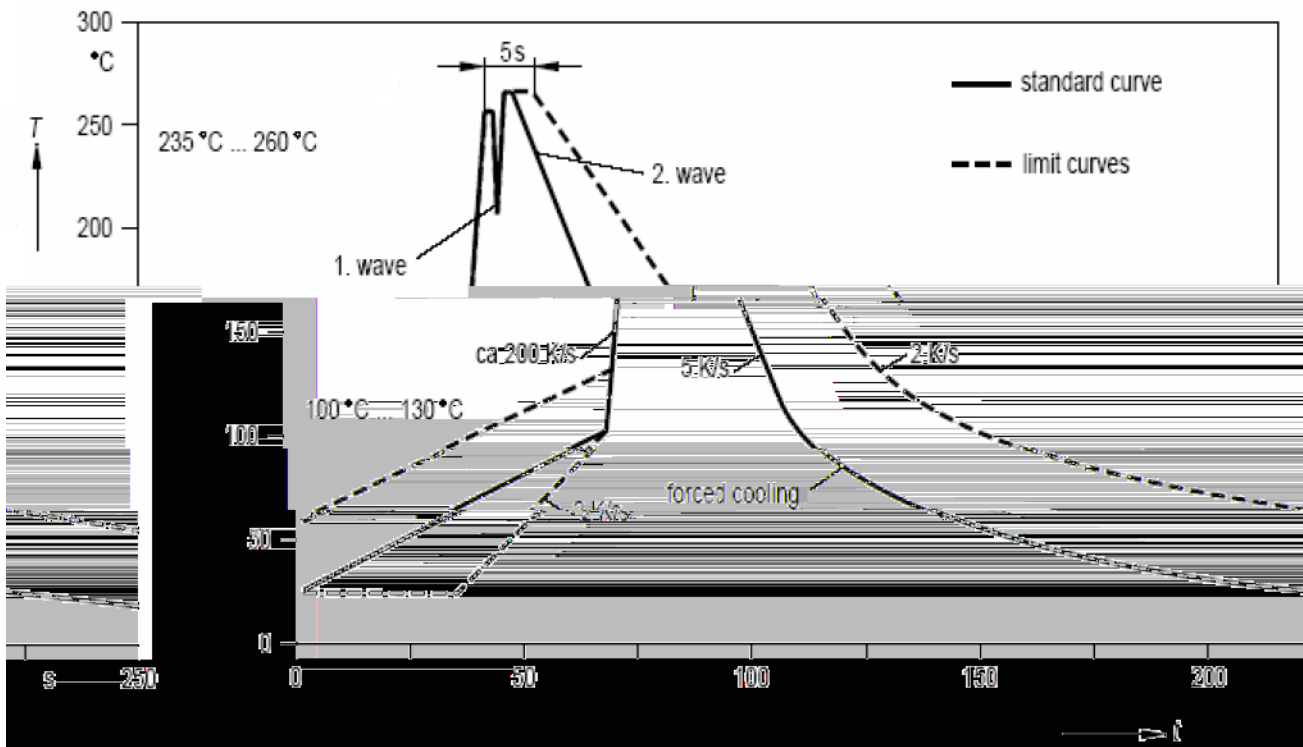
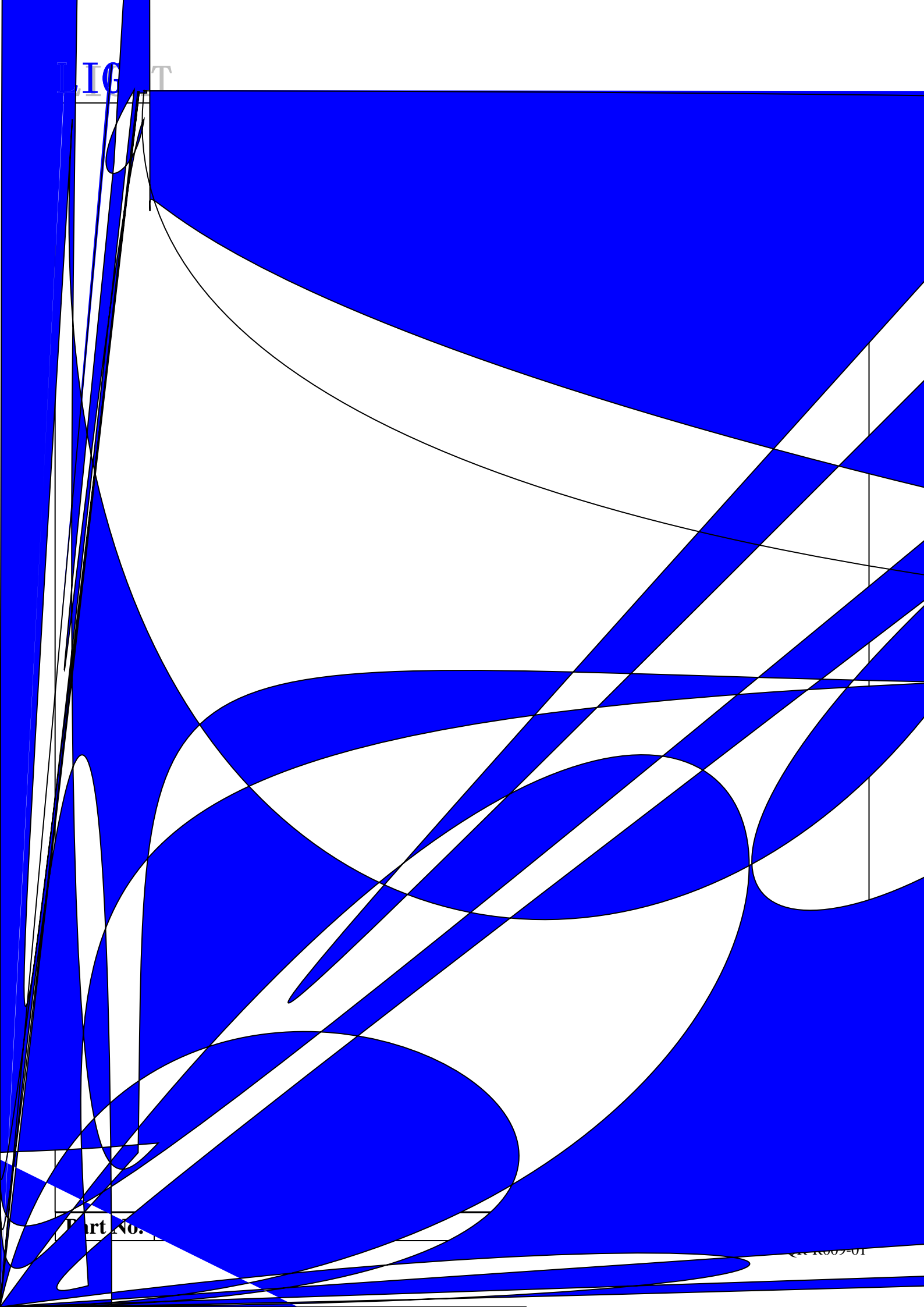


FIG. 1



Part No.

ENR 609-01

## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

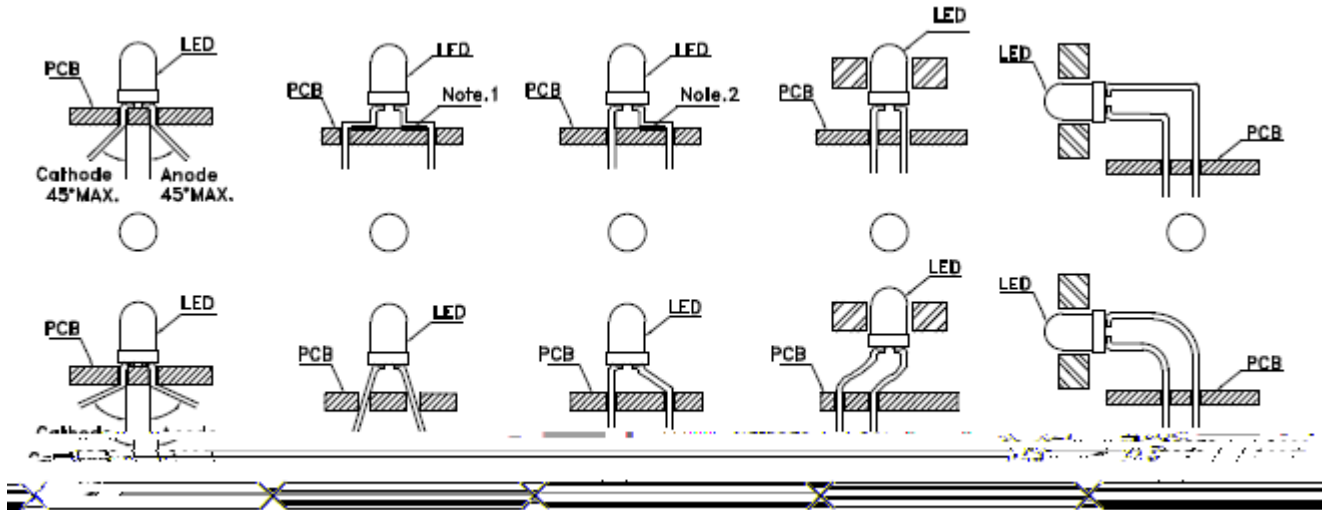


Fig. 1

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

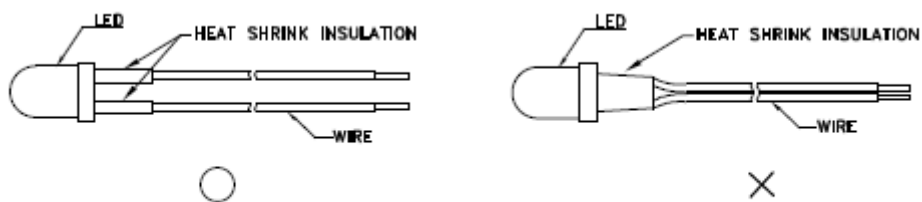
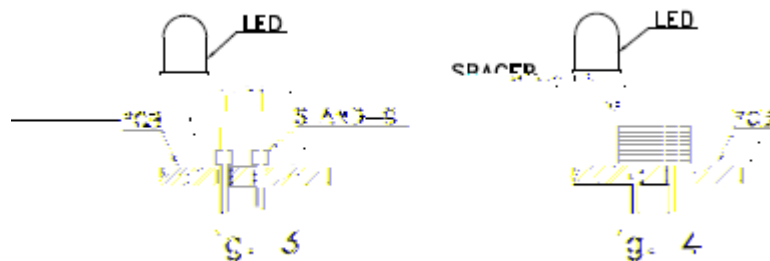
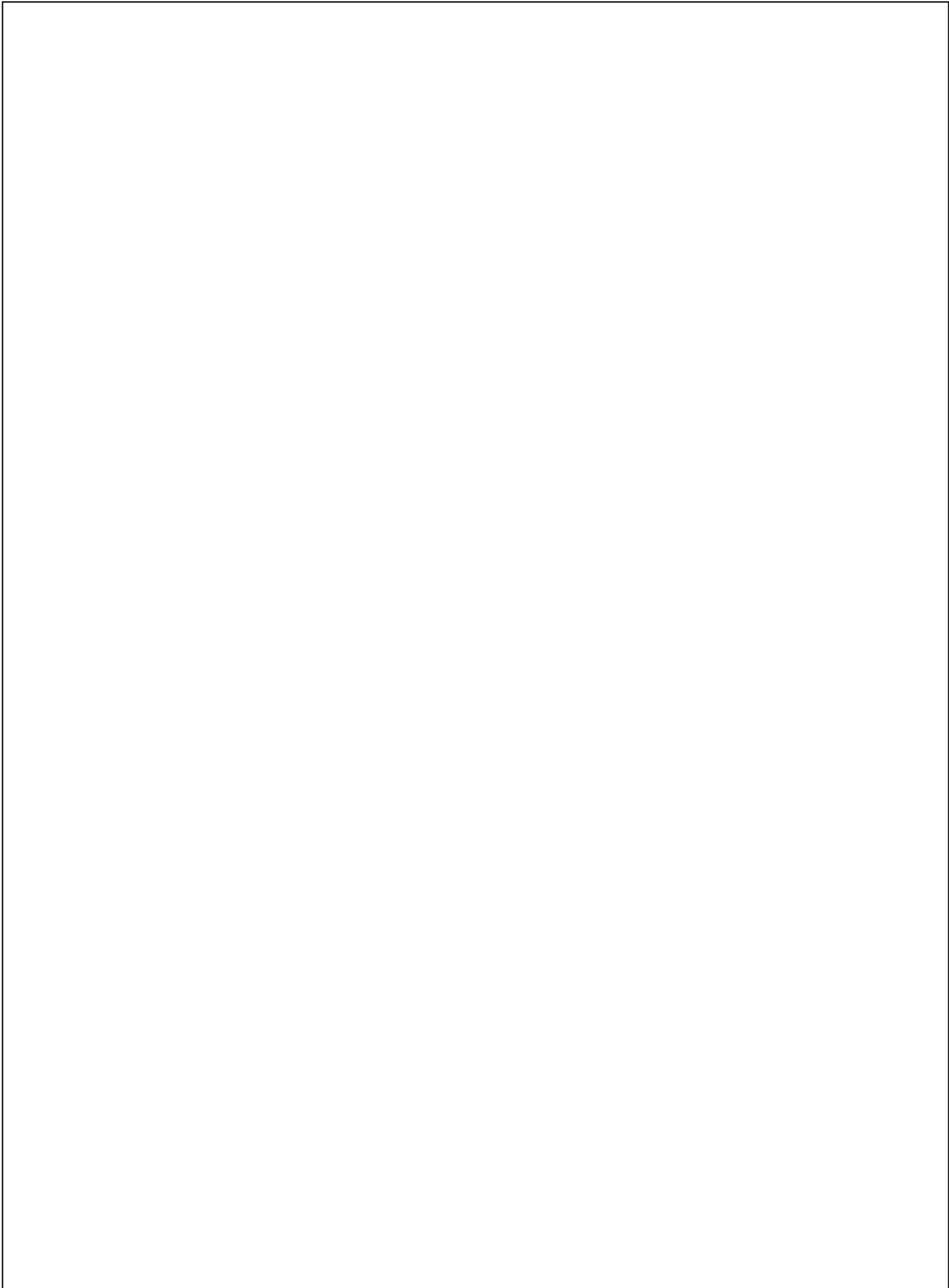


Fig. 2

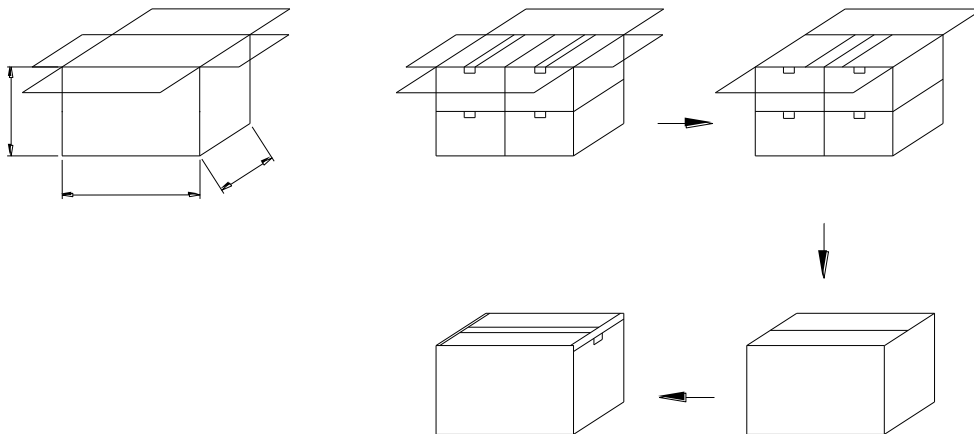
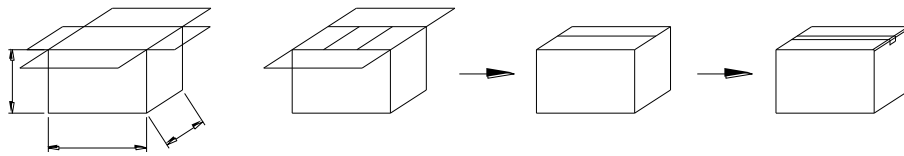
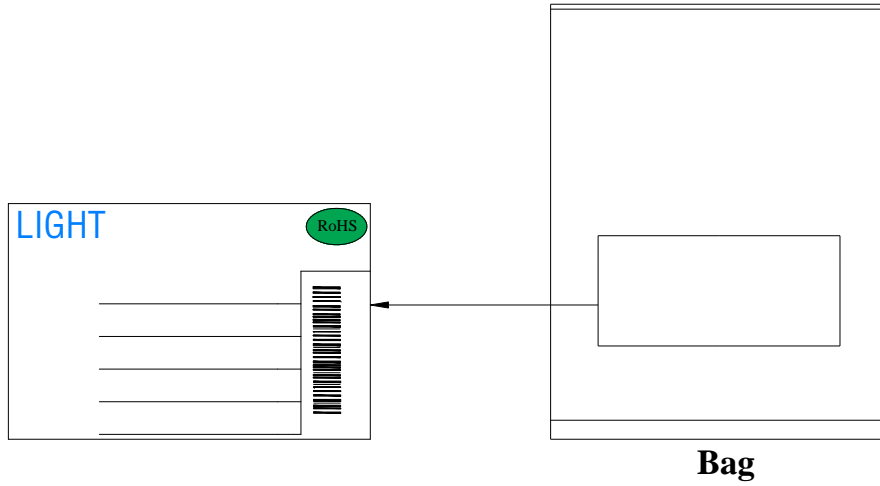
3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



LIGH



## PACKAGE



Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner box volume (Bag / box)	Outer carton volume (Box / Carton)
250	1000	10	4



